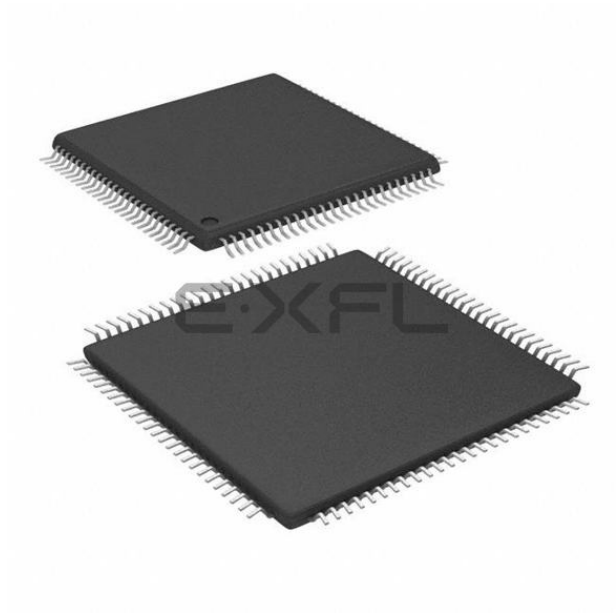
Microchip Technology - DSPIC33FJ128MC710A-H/PT Datasheet



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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	20 MIPS
Connectivity	CANbus, I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, QEI, WDT
Number of I/O	85
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 24x10/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 150°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TQFP
Supplier Device Package	100-TQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj128mc710a-h-pt

Pin Diagrams (Continued)

100-Pin TQFP

■ = Pins are up to 5V tolerant

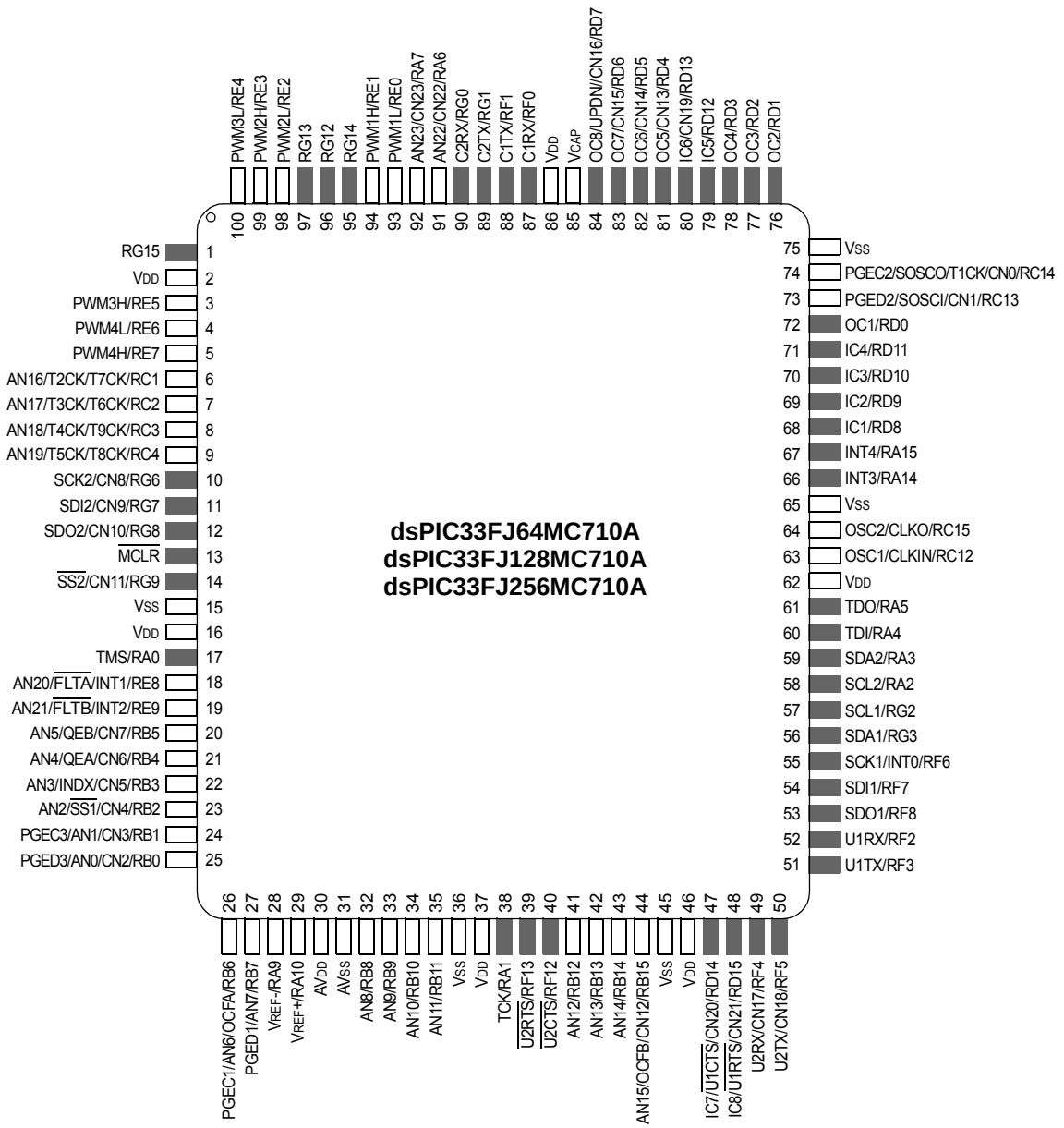
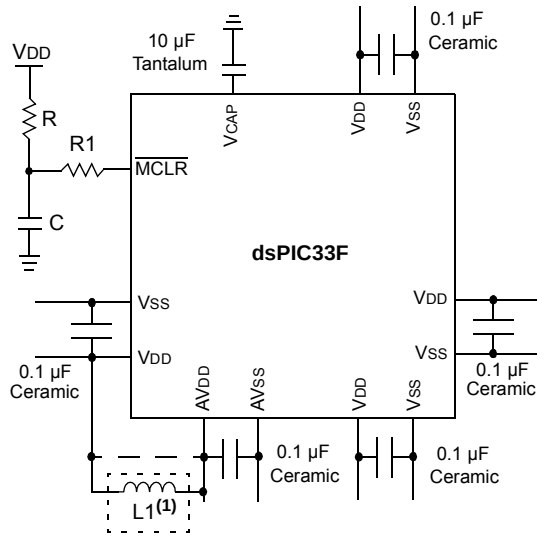


FIGURE 2-1: RECOMMENDED MINIMUM CONNECTION



Note 1: As an option, instead of a hard-wired connection, an inductor (L1) can be substituted between VDD and AVDD to improve ADC noise rejection. The inductor impedance should be less than 1Ω and the inductor capacity greater than 10 mA.

Where:

$$f = \frac{F_{CNV}}{2}$$ (i.e., ADC conversion rate/2)

$$f = \frac{1}{(2\pi\sqrt{LC})}$$

$$L = \left(\frac{1}{(2\pi f\sqrt{C})}\right)^2$$

2.2.1 TANK CAPACITORS

On boards with power traces running longer than six inches in length, it is suggested to use a tank capacitor for integrated circuits including DSCs to supply a local power source. The value of the tank capacitor should be determined based on the trace resistance that connects the power supply source to the device and the maximum current drawn by the device in the application. In other words, select the tank capacitor so that it meets the acceptable voltage sag at the device. Typical values range from 4.7 µF to 47 µF.

2.3 CPU Logic Filter Capacitor Connection (VCAP)

A low-ESR (< 5 Ohms) capacitor is required on the VCAP pin, which is used to stabilize the voltage regulator output voltage. The VCAP pin must not be connected to VDD and must have a capacitor between 4.7 µF and 10 µF, 16V connected to ground. The type can be ceramic or tantalum. Refer to **Section 26.0 "Electrical Characteristics"** for additional information.

The placement of this capacitor should be close to the VCAP. It is recommended that the trace length not exceed one-quarter inch (6 mm). Refer to **Section 23.2 "On-Chip Voltage Regulator"** for details.

2.4 Master Clear (MCLR) Pin

The MCLR pin provides for two specific device functions:

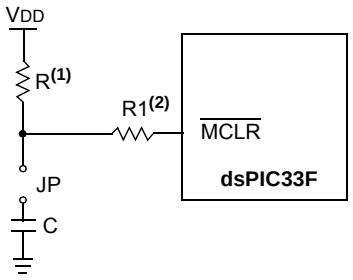
- Device Reset
- Device Programming and Debugging

During device programming and debugging, the resistance and capacitance that can be added to the pin must be considered. Device programmers and debuggers drive the MCLR pin. Consequently, specific voltage levels (VIH and VIL) and fast signal transitions must not be adversely affected. Therefore, specific values of R and C will need to be adjusted based on the application and PCB requirements.

For example, as shown in Figure 2-2, it is recommended that the capacitor, C, be isolated from the MCLR pin during programming and debugging operations.

Place the components shown in Figure 2-2 within one-quarter inch (6 mm) from the MCLR pin.

FIGURE 2-2: EXAMPLE OF MCLR PIN CONNECTIONS



Note 1: R ≤ 10 kΩ is recommended. A suggested starting value is 10 kΩ. Ensure that the MCLR pin VIH and VIL specifications are met.

2: R1 ≤ 470Ω will limit any current flowing into MCLR from the external capacitor, C, in the event of MCLR pin breakdown, due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS). Ensure that the MCLR pin VIH and VIL specifications are met.

3.0 CPU

Note 1: This data sheet summarizes the features of the dsPIC33FJXXXMCX06A/X08A/X10A family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 2. "CPU"** (DS70204) in the *"dsPIC33F/PIC24H Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33FJXXXMCX06A/X08A/X10A CPU module has a 16-bit (data) modified Harvard architecture with an enhanced instruction set, including significant support for DSP. The CPU has a 24-bit instruction word with a variable length opcode field. The Program Counter (PC) is 23 bits wide and addresses up to 4M x 24 bits of user program memory space. The actual amount of program memory implemented varies by device. A single-cycle instruction prefetch mechanism is used to help maintain throughput and provides predictable execution. All instructions execute in a single cycle, with the exception of instructions that change the program flow, the double word move (`MOV.D`) instruction and the table instructions. Overhead-free program loop constructs are supported using the `DO` and `REPEAT` instructions, both of which are interruptible at any point.

The dsPIC33FJXXXMCX06A/X08A/X10A devices have sixteen, 16-bit working registers in the programmer's model. Each of the working registers can serve as a data, address or address offset register. The 16th working register (W15) operates as a software Stack Pointer (SP) for interrupts and calls.

The dsPIC33FJXXXMCX06A/X08A/X10A instruction set has two classes of instructions: MCU and DSP. These two instruction classes are seamlessly integrated into a single CPU. The instruction set includes many addressing modes and is designed for optimum 'C' compiler efficiency. For most instructions, the dsPIC33FJXXXMCX06A/X08A/X10A devices are capable of executing a data (or program data) memory read, a working register (data) read, a data memory write and a program (instruction) memory read per instruction cycle. As a result, three parameter instructions can be supported, allowing A + B = C operations to be executed in a single cycle.

A block diagram of the CPU is shown in Figure 3-1 and the programmer's model for the dsPIC33FJXXXMCX06A/X08A/X10A is shown in Figure 3-2.

3.1 Data Addressing Overview

The data space can be addressed as 32K words or 64 Kbytes, and is split into two blocks referred to as X and Y data memory. Each memory block has its own independent Address Generation Unit (AGU). The MCU class of instructions operates solely through the X memory AGU, which accesses the entire memory map as one linear data space. Certain DSP instructions operate through the X and Y AGUs to support dual operand reads, which splits the data address space into two parts. The X and Y data space boundary is device-specific.

Overhead-free circular buffers (Modulo Addressing mode) are supported in both X and Y address spaces. The Modulo Addressing removes the software boundary checking overhead for DSP algorithms. Furthermore, the X AGU circular addressing can be used with any of the MCU class of instructions. The X AGU also supports Bit-Reversed Addressing to greatly simplify input or output data reordering for radix-2 FFT algorithms.

The upper 32 Kbytes of the data space memory map can optionally be mapped into program space at any 16K program word boundary defined by the 8-bit Program Space Visibility Page register (PSVPAG). The program to data space mapping feature lets any instruction access program space as if it were data space.

The data space also includes 2 Kbytes of DMA RAM, which is primarily used for DMA data transfers but may be used as general purpose RAM.

3.2 DSP Engine Overview

The DSP engine features a high-speed, 17-bit by 17-bit multiplier, a 40-bit ALU, two 40-bit saturating accumulators and a 40-bit bidirectional barrel shifter. The barrel shifter is capable of shifting a 40-bit value up to 16 bits right or left in a single cycle. The DSP instructions operate seamlessly with all other instructions and have been designed for optimal real-time performance. The `MAC` instruction and other associated instructions can concurrently fetch two data operands from memory while multiplying two W registers, and accumulating and optionally saturating the result in the same cycle. This instruction functionality requires that the RAM memory data space be split for these instructions and linear for all others. Data space partitioning is achieved in a transparent and flexible manner through dedicating certain working registers to each address space.

4.0 MEMORY ORGANIZATION

Note 1: This data sheet summarizes the features of the dsPIC33FJXXXMCX06A/X08A/X10A family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 3. "Data Memory"** (DS70202) and **Section 4. "Program Memory"** (DS70203) in the *"dsPIC33F/PIC24H Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

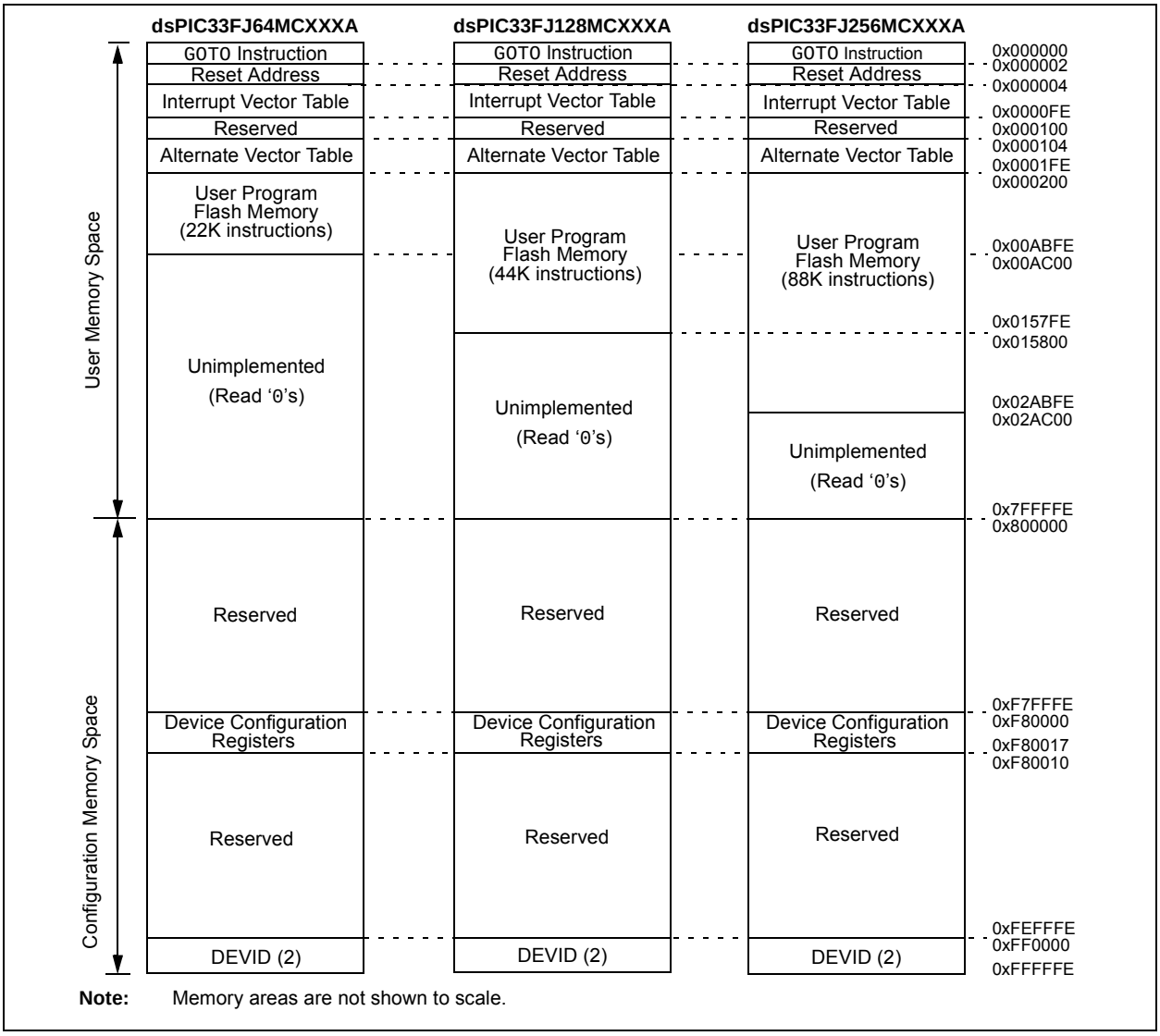
The dsPIC33FJXXXMCX06A/X08A/X10A architecture features separate program and data memory spaces, and buses. This architecture also allows the direct access of program memory from the data space during code execution.

4.1 Program Address Space

The program address memory space of the dsPIC33FJXXXMCX06A/X08A/X10A devices is 4M instructions. The space is addressable by a 24-bit value derived from either the 23-bit Program Counter (PC) during program execution, or from table operation or data space remapping as described in **Section 4.6 "Interfacing Program and Data Memory Spaces"**.

User access to the program memory space is restricted to the lower half of the address range (0x000000 to 0x7FFFFF). The exception is the use of TBLRD/TBLWT operations, which use TBLPAG<7> to permit access to the Configuration bits and Device ID sections of the configuration memory space. Memory usage for the dsPIC33FJXXXMCX06A/X08A/X10A family of devices is shown in Figure 4-1.

FIGURE 4-1: PROGRAM MEMORY MAP FOR dsPIC33FJXXXMCX06A/X08A/X10A DEVICES



Note: Memory areas are not shown to scale.

TABLE 4-17: ADC1 REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
ADC1BUF0	0300	ADC1 Data Buffer 0																xxxx
AD1CON1	0320	ADON	—	ADSIDL	ADDMABM	—	AD12B	FORM<1:0>		SSRC<2:0>			—	SIMSAM	ASAM	SAMP	DONE	0000
AD1CON2	0322	VCFG<2:0>			—	—	CSCNA	CHPS<1:0>		BUFS	—	SMPI<3:0>				BUFM	ALTS	0000
AD1CON3	0324	ADRC	—	—	SAMC<4:0>					ADCS<7:0>								0000
AD1CHS123	0326	—	—	—	—	—	CH123NB<1:0>		CH123SB	—	—	—	—	—	CH123NA<1:0>		CH123SA	0000
AD1CHS0	0328	CH0NB	—	—	CH0SB<4:0>					CH0NA	—	—	CH0SA<4:0>					0000
AD1PCFGH(1)	032A	PCFG31	PCFG30	PCFG29	PCFG28	PCFG27	PCFG26	PCFG25	PCFG24	PCFG23	PCFG22	PCFG21	PCFG20	PCFG19	PCFG18	PCFG17	PCFG16	0000
AD1PCFGL	032C	PCFG15	PCFG14	PCFG13	PCFG12	PCFG11	PCFG10	PCFG9	PCFG8	PCFG7	PCFG6	PCFG5	PCFG4	PCFG3	PCFG2	PCFG1	PCFG0	0000
AD1CSSH(1)	032E	CSS31	CSS30	CSS29	CSS28	CSS27	CSS26	CSS25	CSS24	CSS23	CSS22	CSS21	CSS20	CSS19	CSS18	CSS17	CSS16	0000
AD1CSSL	0330	CSS15	CSS14	CSS13	CSS12	CSS11	CSS10	CSS9	CSS8	CSS7	CSS6	CSS5	CSS4	CSS3	CSS2	CSS1	CSS0	0000
AD1CON4	0332	—	—	—	—	—	—	—	—	—	—	—	—	—	DMABL<2:0>			0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.
Note 1: Not all ANx inputs are available on all devices. Refer to the device pin diagrams for available ANx inputs.

TABLE 4-18: ADC2 REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
ADC2BUF0	0340	ADC2 Data Buffer 0																xxxx
AD2CON1	0360	ADON	—	ADSIDL	ADDMABM	—	AD12B	FORM<1:0>		SSRC<2:0>			—	SIMSAM	ASAM	SAMP	DONE	0000
AD2CON2	0362	VCFG<2:0>			—	—	CSCNA	CHPS<1:0>		BUFS	—	SMPI<3:0>				BUFM	ALTS	0000
AD2CON3	0364	ADRC	—	—	SAMC<4:0>					ADCS<7:0>								0000
AD2CHS123	0366	—	—	—	—	—	CH123NB<1:0>		CH123SB	—	—	—	—	—	CH123NA<1:0>		CH123SA	0000
AD2CHS0	0368	CH0NB	—	—	—	CH0SB<3:0>				CH0NA	—	—	—	CH0SA<3:0>				0000
Reserved	036A	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
AD2PCFGL	036C	PCFG15	PCFG14	PCFG13	PCFG12	PCFG11	PCFG10	PCFG9	PCFG8	PCFG7	PCFG6	PCFG5	PCFG4	PCFG3	PCFG2	PCFG1	PCFG0	0000
Reserved	036E	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
AD2CSSL	0370	CSS15	CSS14	CSS13	CSS12	CSS11	CSS10	CSS9	CSS8	CSS7	CSS6	CSS5	CSS4	CSS3	CSS2	CSS1	CSS0	0000
AD2CON4	0372	—	—	—	—	—	—	—	—	—	—	—	—	—	DMABL<2:0>			0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-25: ECAN2 REGISTER MAP WHEN WIN (C1CTRL<0>) = 1 FOR dsPIC33FJXXXMC708A/710A DEVICES

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
	0500-051E	**See definition when WIN = x**																
C2BUFPNT1	0520	F3BP<3:0>				F2BP<3:0>				F1BP<3:0>				F0BP<3:0>				0000
C2BUFPNT2	0522	F7BP<3:0>				F6BP<3:0>				F5BP<3:0>				F4BP<3:0>				0000
C2BUFPNT3	0524	F11BP<3:0>				F10BP<3:0>				F9BP<3:0>				F8BP<3:0>				0000
C2BUFPNT4	0526	F15BP<3:0>				F14BP<3:0>				F13BP<3:0>				F12BP<3:0>				0000
C2RXM0SID	0530	SID<10:3>								SID<2:0>			—	MIDE	—	EID<17:16>		xxxx
C2RXM0EID	0532	EID<15:8>								EID<7:0>								xxxx
C2RXM1SID	0534	SID<10:3>								SID<2:0>			—	MIDE	—	EID<17:16>		xxxx
C2RXM1EID	0536	EID<15:8>								EID<7:0>								xxxx
C2RXM2SID	0538	SID<10:3>								SID<2:0>			—	MIDE	—	EID<17:16>		xxxx
C2RXM2EID	053A	EID<15:8>								EID<7:0>								xxxx
C2RXF0SID	0540	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C2RXF0EID	0542	EID<15:8>								EID<7:0>								xxxx
C2RXF1SID	0544	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C2RXF1EID	0546	EID<15:8>								EID<7:0>								xxxx
C2RXF2SID	0548	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C2RXF2EID	054A	EID<15:8>								EID<7:0>								xxxx
C2RXF3SID	054C	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C2RXF3EID	054E	EID<15:8>								EID<7:0>								xxxx
C2RXF4SID	0550	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C2RXF4EID	0552	EID<15:8>								EID<7:0>								xxxx
C2RXF5SID	0554	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C2RXF5EID	0556	EID<15:8>								EID<7:0>								xxxx
C2RXF6SID	0558	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C2RXF6EID	055A	EID<15:8>								EID<7:0>								xxxx
C2RXF7SID	055C	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C2RXF7EID	055E	EID<15:8>								EID<7:0>								xxxx
C2RXF8SID	0560	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C2RXF8EID	0562	EID<15:8>								EID<7:0>								xxxx
C2RXF9SID	0564	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C2RXF9EID	0566	EID<15:8>								EID<7:0>								xxxx
C2RXF10SID	0568	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C2RXF10EID	056A	EID<15:8>								EID<7:0>								xxxx

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

REGISTER 7-10: IEC0: INTERRUPT ENABLE CONTROL REGISTER 0 (CONTINUED)

bit 2 **OC1IE:** Output Compare Channel 1 Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 1 **IC1IE:** Input Capture Channel 1 Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 0 **INT0IE:** External Interrupt 0 Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

REGISTER 9-2: CLKDIV: CLOCK DIVISOR REGISTER(2)

R/W-0	R/W-0	R/W-1	R/W-1	R/W-0	R/W-0	R/W-0	R/W-0
ROI	DOZE<2:0>			DOZEN(1)	FRCDIV<2:0>		
bit 15							bit 8

R/W-0	R/W-1	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PLLPOST<1:0>		—	PLLPRE<4:0>				
bit 7							bit 0

Legend:	y = Value set from Configuration bits on POR		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **ROI:** Recover on Interrupt bit
1 = Interrupts will clear the DOZEN bit and the processor clock/peripheral clock ratio is set to 1:1
0 = Interrupts have no effect on the DOZEN bit

bit 14-12 **DOZE<2:0>:** Processor Clock Reduction Select bits
000 = FCY/1
001 = FCY/2
010 = FCY/4
011 = FCY/8 (default)
100 = FCY/16
101 = FCY/32
110 = FCY/64
111 = FCY/128

bit 11 **DOZEN:** DOZE Mode Enable bit(1)
1 = DOZE<2:0> field specifies the ratio between the peripheral clocks and the processor clocks
0 = Processor clock/peripheral clock ratio forced to 1:1

bit 10-8 **FRCDIV<2:0>:** Internal Fast RC Oscillator Postscaler bits
000 = FRC divide by 1 (default)
001 = FRC divide by 2
010 = FRC divide by 4
011 = FRC divide by 8
100 = FRC divide by 16
101 = FRC divide by 32
110 = FRC divide by 64
111 = FRC divide by 256

bit 7-6 **PLLPOST<1:0>:** PLL VCO Output Divider Select bits (also denoted as 'N2', PLL postscaler)
00 = Output/2
01 = Output/4 (default)
10 = Reserved
11 = Output/8

bit 5 **Unimplemented:** Read as '0'

bit 4-0 **PLLPRE<4:0>:** PLL Phase Detector Input Divider bits (also denoted as 'N1', PLL prescaler)
00000 = Input/2 (default)
00001 = Input/3
•
•
•
11111 = Input/33

Note 1: This bit is cleared when the ROI bit is set and an interrupt occurs.
2: This register is reset only on a Power-on Reset (POR).

REGISTER 19-3: I2CxMSK: I2Cx SLAVE MODE ADDRESS MASK REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
—	—	—	—	—	—	AMSK9	AMSK8
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
AMSK7	AMSK6	AMSK5	AMSK4	AMSK3	AMSK2	AMSK1	AMSK0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-10 **Unimplemented:** Read as ‘0’

bit 9-0 **AMSKx:** Mask for Address bit x Select bits

1 = Enable masking for bit x of incoming message address; bit match not required in this position
0 = Disable masking for bit x; bit match required in this position

REGISTER 21-22: CiRXFUL1: ECAN™ RECEIVE BUFFER FULL REGISTER 1

R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0
RXFUL15	RXFUL14	RXFUL13	RXFUL12	RXFUL11	RXFUL10	RXFUL9	RXFUL8
bit 15							bit 8

R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0
RXFUL7	RXFUL6	RXFUL5	RXFUL4	RXFUL3	RXFUL2	RXFUL1	RXFUL0
bit 7							bit 0

Legend:		C= Clearable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **RXFUL15:RXFUL0:** Receive Buffer n Full bits
1 = Buffer is full (set by module)
0 = Buffer is empty (clear by application software)

REGISTER 21-23: CiRXFUL2: ECAN™ RECEIVE BUFFER FULL REGISTER 2

R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0
RXFUL31	RXFUL30	RXFUL29	RXFUL28	RXFUL27	RXFUL26	RXFUL25	RXFUL24
bit 15							bit 8

R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0
RXFUL23	RXFUL22	RXFUL21	RXFUL20	RXFUL19	RXFUL18	RXFUL17	RXFUL16
bit 7							bit 0

Legend:		C= Clearable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **RXFUL31:RXFUL16:** Receive Buffer n Full bits
1 = Buffer is full (set by module)
0 = Buffer is empty (clear by application software)

TABLE 24-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax	Description	# of Words	# of Cycles	Status Flags Affected
11	BTSS	BTSS f,#bit4	Bit Test f, Skip if Set	1	1 (2 or 3)	None
		BTSS Ws,#bit4	Bit Test Ws, Skip if Set	1	1 (2 or 3)	None
12	BTST	BTST f,#bit4	Bit Test f	1	1	Z
		BTST.C Ws,#bit4	Bit Test Ws to C	1	1	C
		BTST.Z Ws,#bit4	Bit Test Ws to Z	1	1	Z
		BTST.C Ws,Wb	Bit Test Ws<Wb> to C	1	1	C
		BTST.Z Ws,Wb	Bit Test Ws<Wb> to Z	1	1	Z
13	BTSTS	BTSTS f,#bit4	Bit Test then Set f	1	1	Z
		BTSTS.C Ws,#bit4	Bit Test Ws to C, then Set	1	1	C
		BTSTS.Z Ws,#bit4	Bit Test Ws to Z, then Set	1	1	Z
14	CALL	CALL lit23	Call Subroutine	2	2	None
		CALL Wn	Call Indirect Subroutine	1	2	None
15	CLR	CLR f	f = 0x0000	1	1	None
		CLR WREG	WREG = 0x0000	1	1	None
		CLR Ws	Ws = 0x0000	1	1	None
		CLR Acc,Wx,Wxd,Wy,Wyd,AWB	Clear Accumulator	1	1	OA,OB,SA,SB
16	CLRWDT	CLRWDT	Clear Watchdog Timer	1	1	WDTO,Sleep
17	COM	COM f	$f = \overline{f}$	1	1	N,Z
		COM f,WREG	$WREG = \overline{f}$	1	1	N,Z
		COM Ws,Wd	$Wd = \overline{Ws}$	1	1	N,Z
18	CP	CP f	Compare f with WREG	1	1	C,DC,N,OV,Z
		CP Wb,#lit5	Compare Wb with lit5	1	1	C,DC,N,OV,Z
		CP Wb,Ws	Compare Wb with Ws (Wb – Ws)	1	1	C,DC,N,OV,Z
19	CP0	CP0 f	Compare f with 0x0000	1	1	C,DC,N,OV,Z
		CP0 Ws	Compare Ws with 0x0000	1	1	C,DC,N,OV,Z
20	CPB	CPB f	Compare f with WREG, with Borrow	1	1	C,DC,N,OV,Z
		CPB Wb,#lit5	Compare Wb with lit5, with Borrow	1	1	C,DC,N,OV,Z
		CPB Wb,Ws	Compare Wb with Ws, with Borrow ($Wb – Ws – \overline{C}$)	1	1	C,DC,N,OV,Z
21	CPSEQ	CPSEQ Wb, Wn	Compare Wb with Wn, Skip if =	1	1 (2 or 3)	None
22	CPSGT	CPSGT Wb, Wn	Compare Wb with Wn, Skip if >	1	1 (2 or 3)	None
23	CPSLT	CPSLT Wb, Wn	Compare Wb with Wn, Skip if <	1	1 (2 or 3)	None
24	CPSNE	CPSNE Wb, Wn	Compare Wb with Wn, Skip if ≠	1	1 (2 or 3)	None
25	DAW	DAW Wn	Wn = Decimal Adjust Wn	1	1	C
26	DEC	DEC f	f = f – 1	1	1	C,DC,N,OV,Z
		DEC f,WREG	WREG = f – 1	1	1	C,DC,N,OV,Z
		DEC Ws,Wd	Wd = Ws – 1	1	1	C,DC,N,OV,Z
27	DEC2	DEC2 f	f = f – 2	1	1	C,DC,N,OV,Z
		DEC2 f,WREG	WREG = f – 2	1	1	C,DC,N,OV,Z
		DEC2 Ws,Wd	Wd = Ws – 2	1	1	C,DC,N,OV,Z
28	DISI	DISI #lit14	Disable Interrupts for k Instruction Cycles	1	1	None
29	DIV	DIV.S Wm,Wn	Signed 16/16-bit Integer Divide	1	18	N,Z,C,OV
		DIV.SD Wm,Wn	Signed 32/16-bit Integer Divide	1	18	N,Z,C,OV
		DIV.U Wm,Wn	Unsigned 16/16-bit Integer Divide	1	18	N,Z,C,OV
		DIV.UD Wm,Wn	Unsigned 32/16-bit Integer Divide	1	18	N,Z,C,OV
30	DIVF	DIVF Wm,Wn	Signed 16/16-bit Fractional Divide	1	18	N,Z,C,OV
31	DO	DO #lit14,Expr	Do Code to PC + Expr, lit14 + 1 Times	2	2	None
		DO Wn,Expr	Do Code to PC + Expr, (Wn) + 1 Times	2	2	None
32	ED	ED Wm*Wm,Acc,Wx,Wy,Wxd	Euclidean Distance (no accumulate)	1	1	OA,OB,OAB, SA,SB,SAB
33	EDAC	EDAC Wm*Wm,Acc,Wx,Wy,Wxd	Euclidean Distance	1	1	OA,OB,OAB, SA,SB,SAB

TABLE 26-6: DC CHARACTERISTICS: IDLE CURRENT (IIDLE)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Parameter No.(3)	**Typical(2)**	**Max**	**Units**	**Conditions**		
Idle Current (IIDLE): Core Off, Clock On Base Current(1)						
DC40d	3	25	mA	-40°C	3.3V	10 MIPS
DC40a	3	25	mA	+25°C		
DC40b	3	25	mA	+85°C		
DC40c	3	25	mA	+125°C		
DC41d	4	25	mA	-40°C	3.3V	16 MIPS
DC41a	5	25	mA	+25°C		
DC41b	6	25	mA	+85°C		
DC41c	6	25	mA	+125°C		
DC42d	8	25	mA	-40°C	3.3V	20 MIPS
DC42a	9	25	mA	+25°C		
DC42b	10	25	mA	+85°C		
DC42c	10	25	mA	+125°C		
DC43a	15	25	mA	+25°C	3.3V	30 MIPS
DC43d	15	25	mA	-40°C		
DC43b	15	25	mA	+85°C		
DC43c	15	25	mA	+125°C		
DC44d	16	25	mA	-40°C	3.3V	40 MIPS
DC44a	16	25	mA	+25°C		
DC44b	16	25	mA	+85°C		
DC44c	16	25	mA	+125°C		

Note 1: Base IIDLE current is measured as follows:

- CPU core is off, oscillator is configured in EC mode and external clock active, OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration word
- All I/O pins are configured as inputs and pulled to VSS
- $\overline{MCLR}$ = VDD, WDT and FSCM are disabled
- No peripheral modules are operating; however, every peripheral is being clocked (defined PMDx bits are set to zero and unimplemented PMDx bits are set to one)
- JTAG is disabled

2: These parameters are characterized but not tested in manufacturing.

3: Data in “Typ” column is at 3.3V, +25ºC unless otherwise stated.

TABLE 26-7: DC CHARACTERISTICS: POWER-DOWN CURRENT (I_{PD})

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Parameter No.(3)	**Typical(2)**	**Max**	**Units**	**Conditions**		
Power-Down Current (I_{PD})(1)						
DC60d	50	200	µA	-40°C	3.3V	Base Power-Down Current(3)
DC60a	50	200	µA	+25°C		
DC60b	200	500	µA	+85°C		
DC60c	600	1000	µA	+125°C		
DC61d	8	13	µA	-40°C	3.3V	Watchdog Timer Current: ΔI_{WDT}(3)
DC61a	10	15	µA	+25°C		
DC61b	12	20	µA	+85°C		
DC61c	13	25	µA	+125°C		

Note 1: I_{PD} (Sleep) current is measured as follows:

- CPU core is off, oscillator is configured in EC mode and external clock active, OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration word
- All I/O pins are configured as inputs and pulled to V_{SS}
- $\overline{MCLR}$ = V_{DD}, WDT and FSCM are disabled, all peripheral modules except the ADC are disabled (PMDx bits are all '1's). The following ADC settings are enabled for each ADC module (ADCx) prior to executing the PWRSAV instruction: ADON = 1, VCFG = 1, AD12B = 1 and ADxMD = 0.
- VREGS bit (RCON<8>) = 0 (i.e., core regulator is set to stand-by while the device is in Sleep mode)
- RTCC is disabled.
- JTAG is disabled

2: Data in the "Typ" column is at 3.3V, +25ºC unless otherwise stated.

3: The Watchdog Timer Current is the additional current consumed when the WDT module is enabled. This current should be added to the base I_{PD} current.

4: These currents are measured on the device containing the most memory in this family.

5: These parameters are characterized, but are not tested in manufacturing.

TABLE 26-9: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS (CONTINUED)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
DI60a	IICL	**Input Low Injection Current**	0	—	-5(5,8)	mA	All pins except VDD, VSS, AVDD, AVSS, MCLR, VCAP, SOSCI, SOSCO, and RB11
DI60b	IICH	**Input High Injection Current**	0	—	+5(6,7,8)	mA	All pins except VDD, VSS, AVDD, AVSS, MCLR, VCAP, SOSCI, SOSCO, RB11, and all 5V tolerant pins(7)
DI60c	∑IICT	**Total Input Injection Current (sum of all I/O and control pins)**	-20(9)	—	+20(9)	mA	Absolute instantaneous sum of all ± input injection currents from all I/O pins (| IICL + | IICH |) ≤ ∑IICT

Note 1: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

2: The leakage current on the MCLR pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

4: See **"Pin Diagrams"** for a list of 5V tolerant pins.

5: VIL source < (VSS – 0.3). Characterized but not tested.

6: Non-5V tolerant pins VIH source > (VDD + 0.3), 5V tolerant pins VIH source > 5.5V. Characterized but not tested.

7: Digital 5V tolerant pins cannot tolerate any "positive" input injection current from input sources > 5.5V.

8: Injection currents > | 0 | can affect the ADC results by approximately 4-6 counts.

9: Any number and/or combination of I/O pins not excluded under IICL or IICH conditions are permitted provided the mathematical "absolute instantaneous" sum of the input injection currents from all pins do not exceed the specified limit. Characterized but not tested.

TABLE 26-11: ELECTRICAL CHARACTERISTICS: BOR

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min(1)**	**Typ**	**Max(1)**	**Units**	**Conditions**
BO10	VBOR	BOR Event on VDD Transition High-to-Low	2.40	—	2.55	V	VDD

Note 1: Parameters are for design guidance only and are not tested in manufacturing.

TABLE 26-12: DC CHARACTERISTICS: PROGRAM MEMORY

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
		Program Flash Memory					
D130	EP	Cell Endurance	10,000	—	—	E/W	—
D131	VPR	VDD for Read	VMIN	—	3.6	V	VMIN = Minimum operating voltage
D132b	VPEW	VDD for Self-Timed Write	VMIN	—	3.6	V	VMIN = Minimum operating voltage
D134	TRETD	Characteristic Retention	20	—	—	Year	Provided no other specifications are violated
D135	IDDP	Supply Current during Programming	—	10	—	mA	—
D136a	TRW	Row Write Time	1.32	—	1.74	ms	TRW = 11064 FRC cycles, TA = +85°C, see **Note 2**
D136b	TRW	Row Write Time	1.28	—	1.79	ms	TRW = 11064 FRC cycles, TA = +150°C, see **Note 2**
D137a	TPE	Page Erase Time	20.1	—	26.5	ms	TPE = 168517 FRC cycles, TA = +85°C, see **Note 2**
D137b	TPE	Page Erase Time	19.5	—	27.3	ms	TPE = 168517 FRC cycles, TA = +150°C, see **Note 2**
D138a	TWW	Word Write Cycle Time	42.3	—	55.9	µs	TWW = 355 FRC cycles, TA = +85°C, see **Note 2**
D138b	TWW	Word Write Cycle Time	41.1	—	57.6	µs	TWW = 355 FRC cycles, TA = +150°C, see **Note 2**

Note 1: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

2: Other conditions: FRC = 7.37 MHz, TUN<5:0> = b'011111 (for Min), TUN<5:0> = b'100000 (for Max). This parameter depends on the FRC accuracy (see Table 26-19) and the value of the FRC Oscillator Tuning register (see Register 9-4). For complete details on calculating the Minimum and Maximum time, see **Section 5.3 "Programming Operations"**.

TABLE 26-13: INTERNAL VOLTAGE REGULATOR SPECIFICATIONS

Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended							
Param.	**Symbol**	**Characteristics**	**Min**	**Typ**	**Max**	**Units**	**Comments**
—	CEFC	External Filter Capacitor Value	4.7	10	—	µF	Capacitor must be low series resistance (< 5 ohms)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature			
Parameter No.	**Typical**	**Max**	**Units**	**Conditions**		
Power-Down Current (IPD)						
HDC61c	3	5	µA	+150°C	3.3V	Watchdog Timer Current: ΔIWDT(2,4)

Note 1: Base IPD is measured with all peripherals and clocks shut down. All I/Os are configured as inputs and pulled to VSS. WDT, etc., are all switched off, and VREGS (RCON<8>) = 1.

2: The Δ current is the additional current consumed when the module is enabled. This current should be added to the base IPD current.

3: These currents are measured on the device containing the most memory in this family.

4: These parameters are characterized, but are not tested in manufacturing.

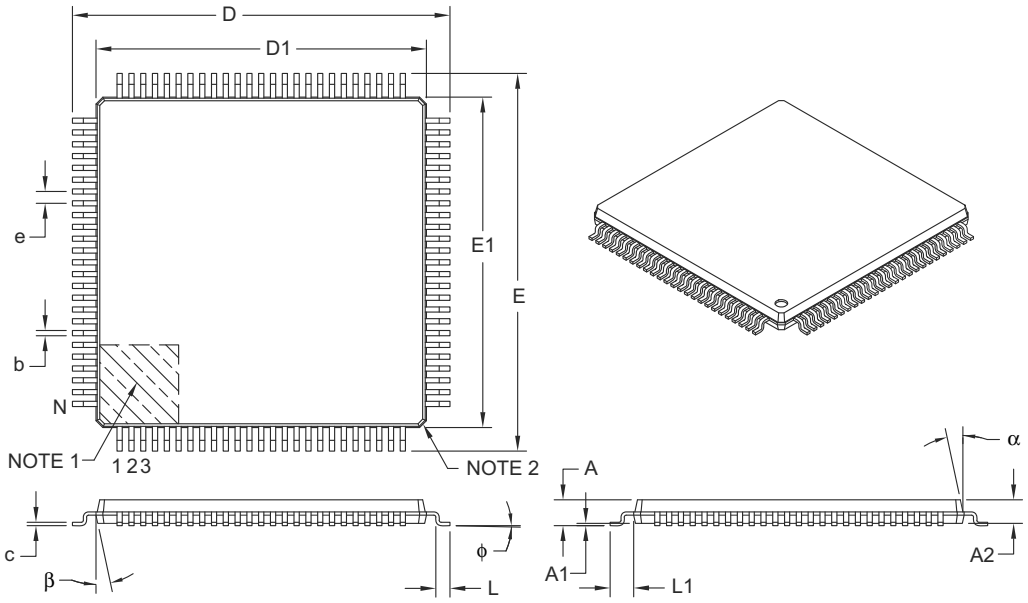
TABLE 27-5: DC CHARACTERISTICS: DOZE CURRENT (IDOZE)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature				
Parameter No.	**Typical(1)**	**Max**	**Doze Ratio**	**Units**	**Conditions**		
HDC72a	39	45	1:2	mA	+150°C	3.3V	20 MIPS
HDC72f	18	25	1:64	mA			
HDC72g	18	25	1:128	mA			

Note 1: Parameters with Doze ratios of 1:2 and 1:64 are characterized, but are not tested in manufacturing.

100-Lead Plastic Thin Quad Flatpack (PF) – 14x14x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		100	
Lead Pitch	e		0.50 BSC	
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	ϕ	0°	3.5°	7°
Overall Width	E		16.00 BSC	
Overall Length	D		16.00 BSC	
Molded Package Width	E1		14.00 BSC	
Molded Package Length	D1		14.00 BSC	
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.17	0.22	0.27
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-110B

APPENDIX A: MIGRATING FROM dsPIC33FJXXXMCX06/X08/X10 DEVICES TO dsPIC33FJXXXMCX06A/X08A/X10A DEVICES

The dsPIC33FJXXXMCX06A/X08A/X10A devices were designed to enhance the dsPIC33FJXXXMCX06/X08/X10 families of devices.

In general, the dsPIC33FJXXXMCX06A/X08A/X10A devices are backward-compatible with dsPIC33FJXXXMCX06/X08/X10 devices; however, manufacturing differences may cause dsPIC33FJXXXMCX06A/X08A/X10A devices to behave differently from dsPIC33FJXXXMCX06/X08/X10 devices. Therefore, complete system test and characterization is recommended if dsPIC33FJXXXMCX06A/X08A/X10A devices are used to replace dsPIC33FJXXXMCX06/X08/X10 devices.

The following enhancements were introduced:

- Extended temperature support of up to +125ºC
- Enhanced Flash module with higher endurance and retention
- New PLL Lock Enable Configuration bit
- Added Timer5 trigger for ADC1 and Timer3 trigger for ADC2

Revision C (March 2011)

This revision includes typographical and formatting changes throughout the data sheet text. In addition, all instances of VDDCORE have been removed.

All other major changes are referenced by their respective section in the following table.

TABLE B-2: MAJOR SECTION UPDATES

Section Name	Update Description
Section 2.0 "Guidelines for Getting Started with 16-bit Digital Signal Controllers"	Updated the title of **Section 2.3 "CPU Logic Filter Capacitor Connection (VCAP)"**. The frequency limitation for device PLL start-up conditions was updated in **Section 2.7 "Oscillator Value Conditions on Device Start-up"**. The second paragraph in **Section 2.9 "Unused I/Os"** was updated.
Section 4.0 "Memory Organization"	The All Resets values for the following SFRs in the Timer Register Map were changed (see Table 4-6): • TMR1 • TMR2 • TMR3 • TMR4 • TMR5 • TMR6 • TMR7 • TMR8 • TMR9
Section 9.0 "Oscillator Configuration"	Added Note 3 to the OSCCON: Oscillator Control Register (see Register 9-1). Added Note 2 to the CLKDIV: Clock Divisor Register (see Register 9-2). Added Note 1 to the PLLFBD: PLL Feedback Divisor Register (see Register 9-3). Added Note 2 to the OSCTUN: FRC Oscillator Tuning Register (see Register 9-4).
Section 22.0 "10-bit/12-bit Analog-to-Digital Converter (ADC)"	Updated the VREFL references in the ADC1 module block diagram (see Figure 22-1).
Section 23.0 "Special Features"	Added a new paragraph and removed the third paragraph in **Section 23.1 "Configuration Bits"**. Added the column "RTSP Effects" to the Configuration Bits Descriptions (see Table 23-2).

Revision D (June 2012)

This revision includes typographical and formatting changes throughout the data sheet text.

All other major changes are referenced by their respective section in the following table.

TABLE B-3: MAJOR SECTION UPDATES

Section Name	Update Description
Section 2.0 "Guidelines for Getting Started with 16-bit Digital Signal Controllers"	Updated the Recommended Minimum Connection (see Figure 2-1).
Section 9.0 "Oscillator Configuration"	Updated the COSC<2:0> and NOSC<2:0> bit value definitions for '001' (see Register 9-1).
Section 22.0 "10-bit/12-bit Analog-to-Digital Converter (ADC)"	Updated the Analog-to-Digital Conversion Clock Period Block Diagram (see Figure 22-2).
Section 23.0 "Special Features"	Added Note 3 to the On-chip Voltage Regulator Connections (see Figure 23-1).
Section 26.0 "Electrical Characteristics"	Updated **"Absolute Maximum Ratings"**. Updated Operating MIPS vs. Voltage (see Table 26-1). Removed parameter DC18 from the DC Temperature and Voltage Specifications (see Table 26-4). Updated the notes in the following tables: • Table 26-5 • Table 26-6 • Table 26-7 • Table 26-8 Updated the I/O Pin Output Specifications (see Table 26-10). Updated the Conditions for parameter BO10 (see Table 26-11). Updated the Conditions for parameters D136b, D137b and D138b (T_A = 150ºC) (see Table 26-12).
Section 27.0 "High Temperature Electrical Characteristics"	Updated **"Absolute Maximum Ratings(1)"**. Updated the I/O Pin Output Specifications (see Table 27-6). Removed Table 26-7: DC Characteristics: Program Memory.